

PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| Yuhsuke Matsumoto | 09/01/2011 |
| Tatsumi Tsuchiya | 09/01/2011 |
| Eiki Oosawa | 09/01/2011 |
| Tatsushi Yoshida | 09/01/2011 |
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| City: | Amsterdam |
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| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 13229631 |
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PATENT

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ASSIGNMENT FOR PATENT APPLICATION

Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

HEAD-GIMBAL ASSEMBLY WITH A SUSPENSION-LEAD PAD HAVING A FORM THAT IS CONFIGURED TO INHIBIT FORMATION OF AN INTER-PAD SOLDER BRIDGE

Whereas, **Hitachi Global Storage Technologies Netherlands B.V.**, having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands (hereinafter referred to as "HITACHI"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature: 松本祐介 Date: 2011-09-01
Typed Name: Yuhsuke MATSUMOTO
- 2) Signature: 土屋辰己 Date: 2011-09-01
Typed Name: Tatsumi TSUCHIYA
- 3) Signature: 大澤英紀 Date: 2011-09-01
Typed Name: Eiki OOSAWA
- 4) Signature: 吉田達士 Date: 2011-09-01
Typed Name: Tatsushi YOSHIDA